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United States Patent [19]

Sadigh-Behzadi

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[54] **INTEGRATED CIRCUIT ELECTRONIC PACKAGE**

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[73] Assignee: **Cicon Components, Inc.,** Chatsworth, Calif.

[**] Term: **14 Years**

[21] Appl. No.: **9,137**

[22] Filed: **Jun. 4, 1993**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/147, 182; 439/55, 439/65, 68, 70, 72, 76; 361/752, 783, 820; 174/52.4

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Attorney, Agent, or Firm—Knobbe, Martens, Olson & Bear

[57] **CLAIM**

The ornamental design for an integrated circuit electronic package, as shown and described.

DESCRIPTION

FIG. **1** is a left, front perspective view showing my new integrated circuit electronic package design as it is attached to an integrated circuit;

FIG. **2** is a front elevational view thereof;

FIG. **3** is a rear elevational view thereof;

FIG. **4** is a top plan view thereof;

FIG. **5** is a bottom plan view thereof; and,

FIG. **6** is a right side elevational view thereof which is a mirror image of the left side elevational view.

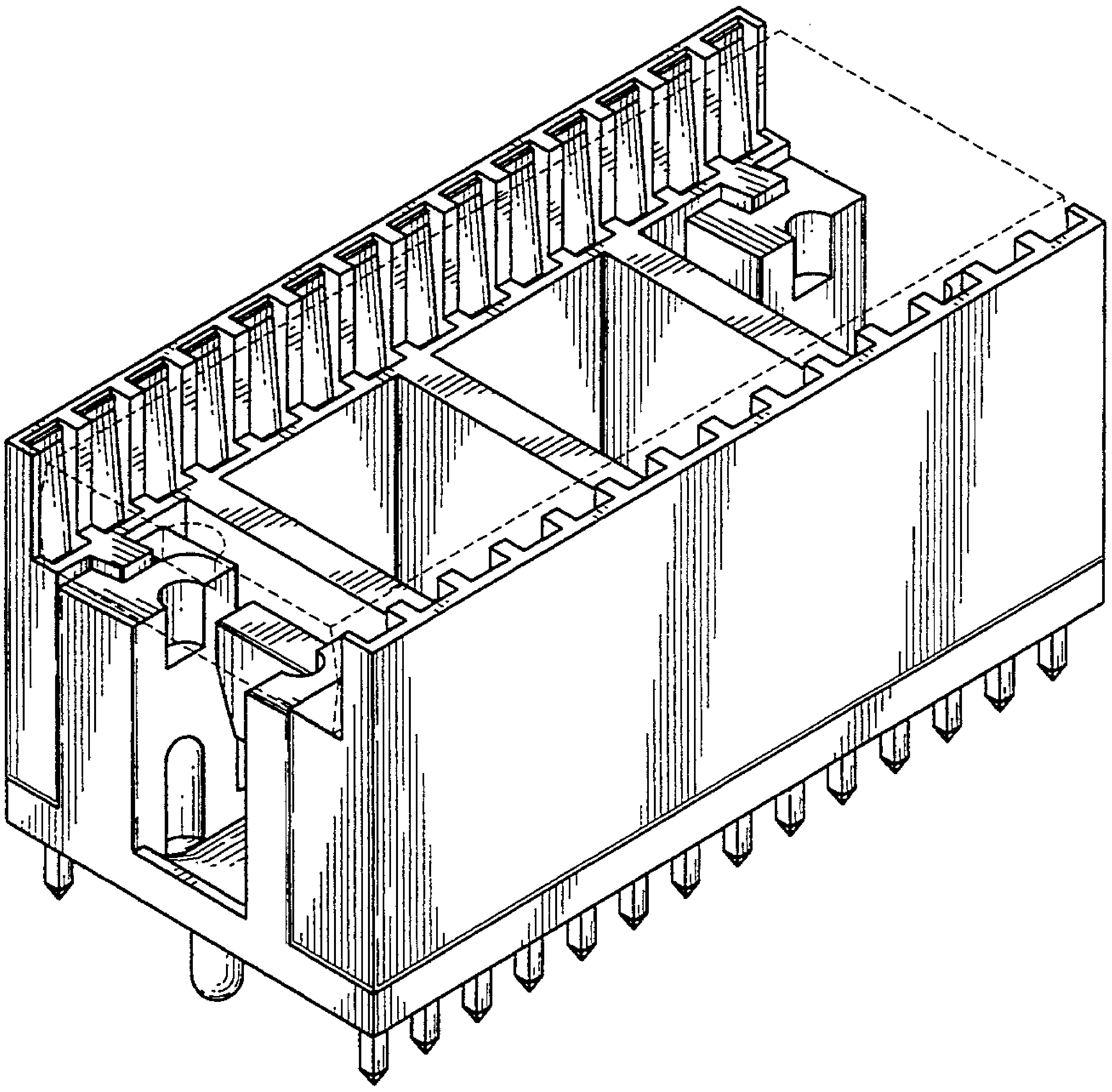

Fig. 1

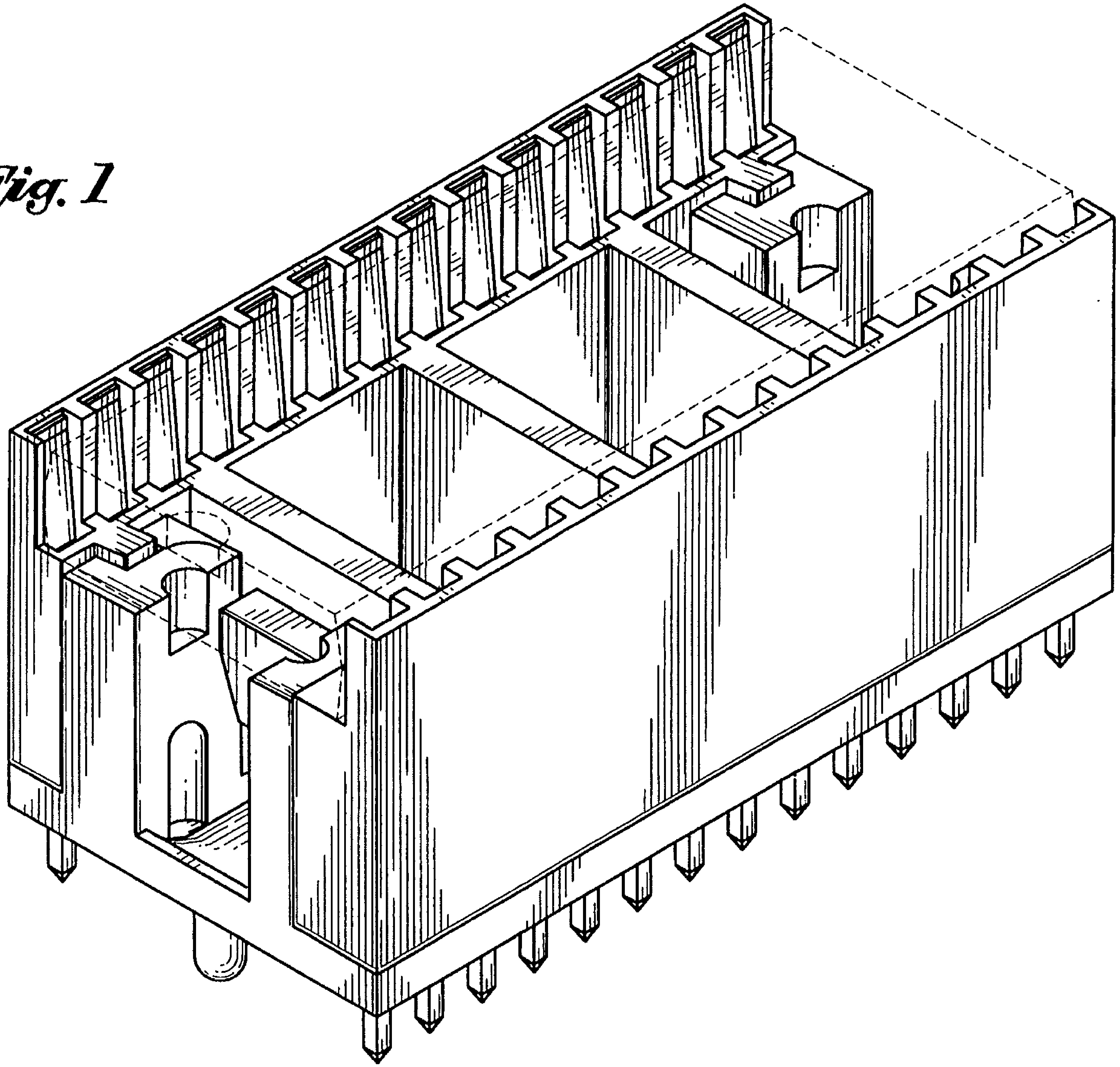

Fig. 2

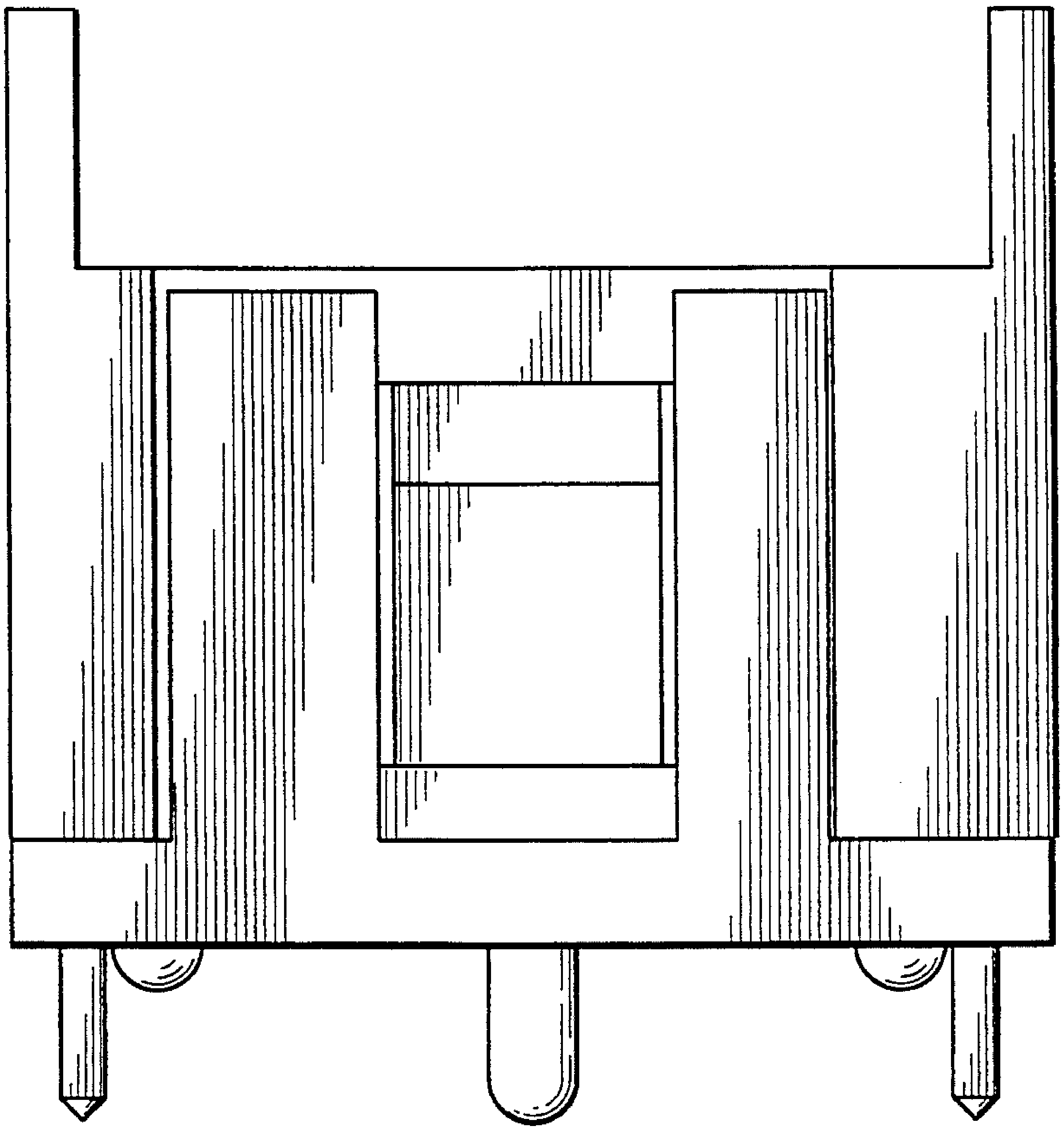

Fig. 3

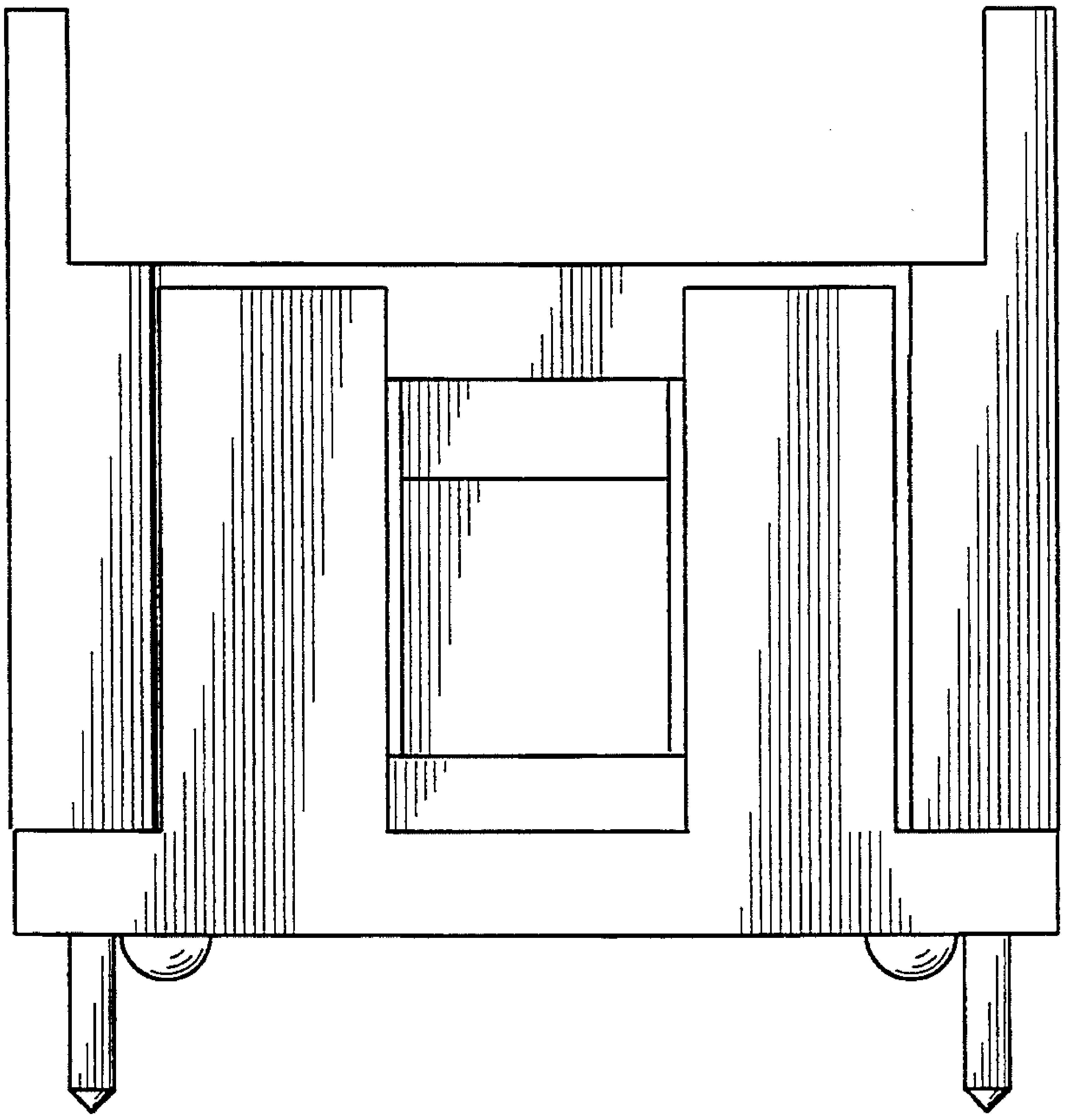

Fig. 4

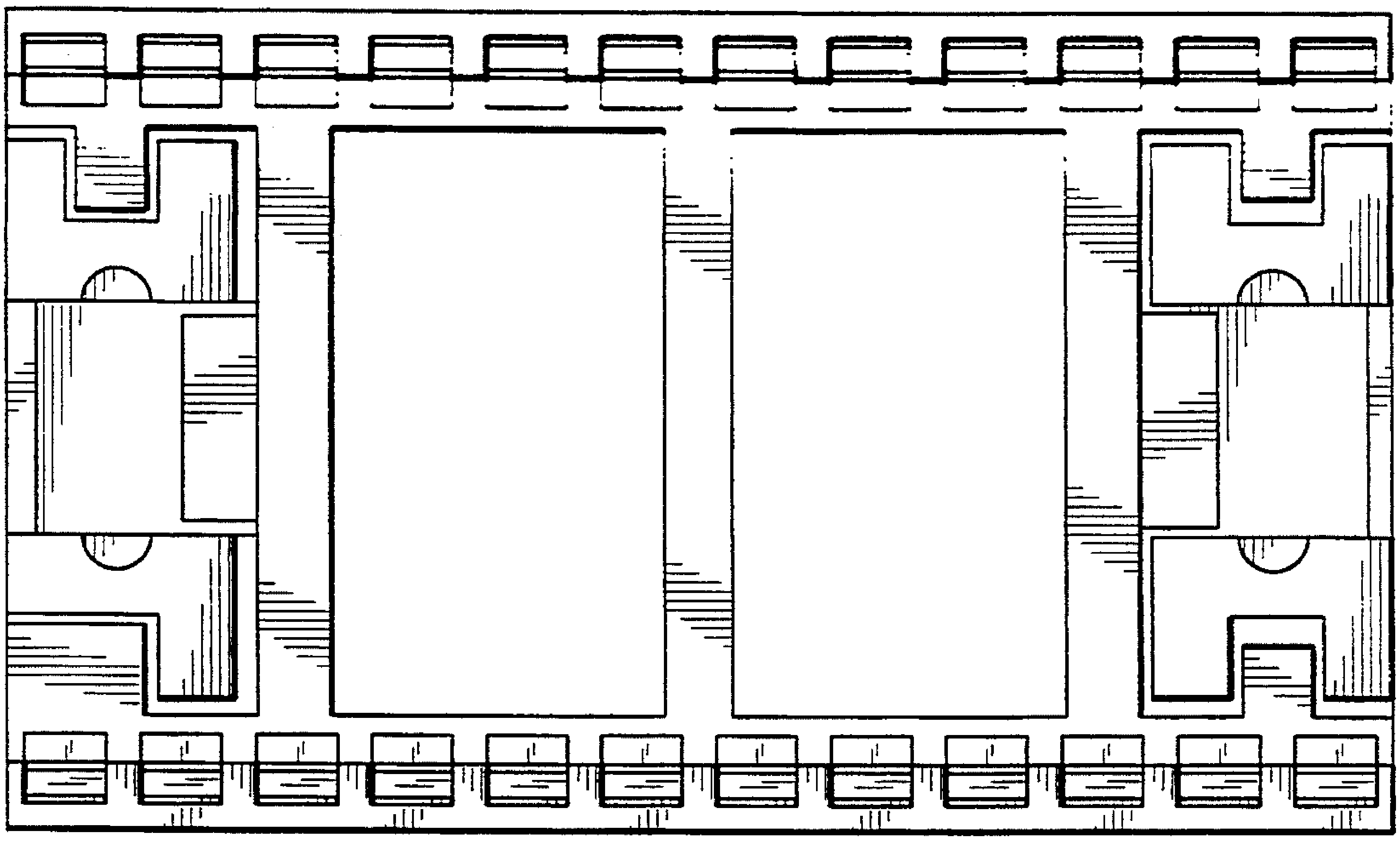

Fig. 5

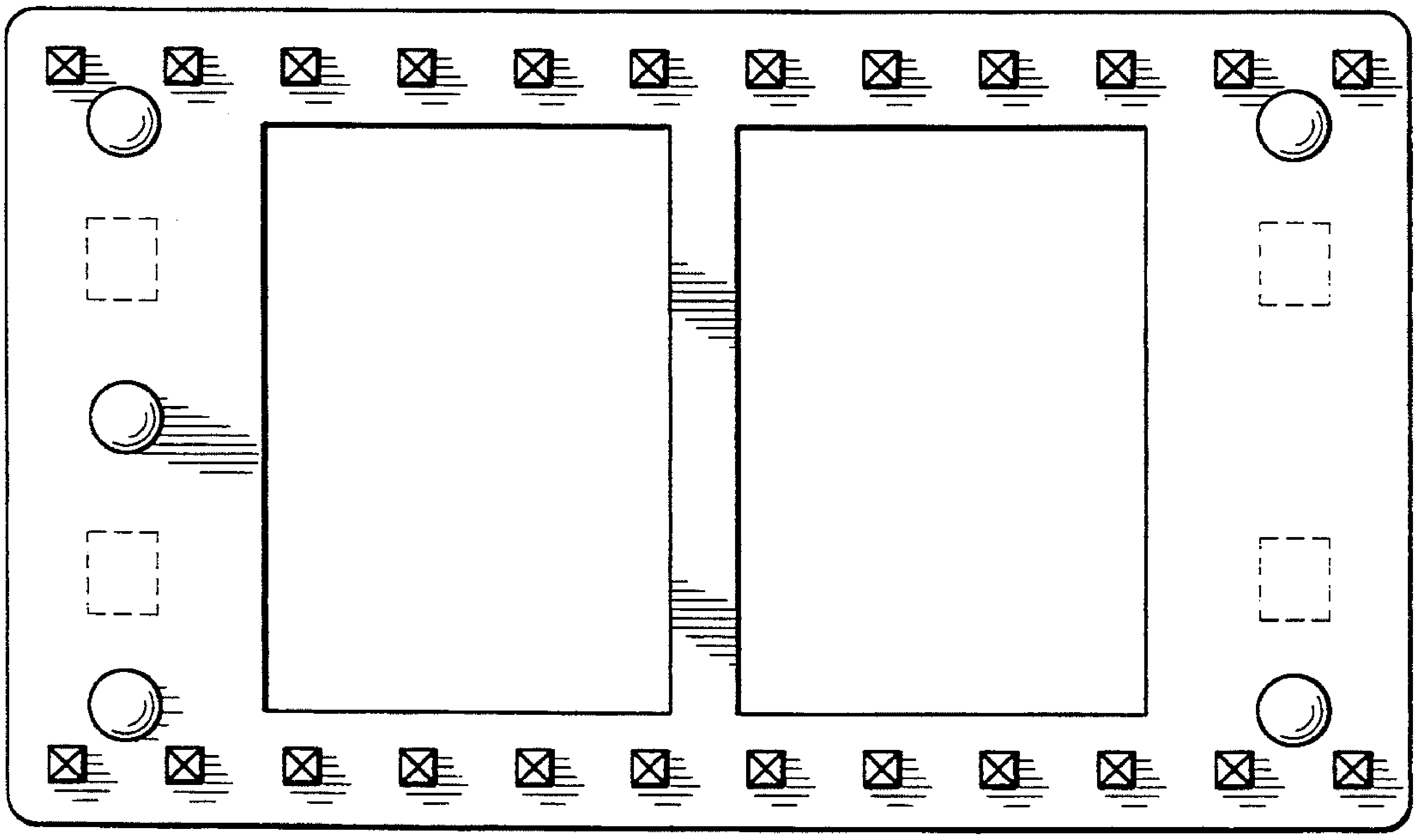

Fig. 6